

NOTES:

1.MATERIALS: PHOSPHOR BRONZE(C5191-H)

2.BURR: 0.05MAX;WARPAGE: 0.10MAX

3.Wire Range: AWG#22

4.PLATING:

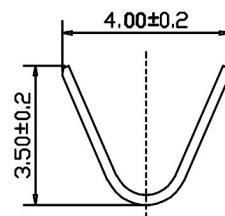
(1) BECHICS CLASH AFTER PLATING: 20u'MIN Ni;80u'MIN TIN;CONTACT AREA GOLD: 0.5u'
REEK SALT TEST 12H MIN

(2) BECHICS CLASH AFTER PLATING: 20u'MIN Ni;80u'MIN TIN;CONTACT AREA GOLD: 3u'
REEK SALT TEST 12H MIN

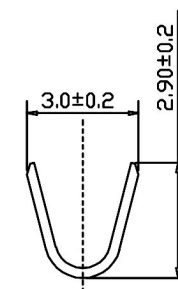
5.LOOSE CONTACT: RETENTION FORCE: 2.5kg MIN

6.REQUIRE : cd≤5ppm pb≤50ppm

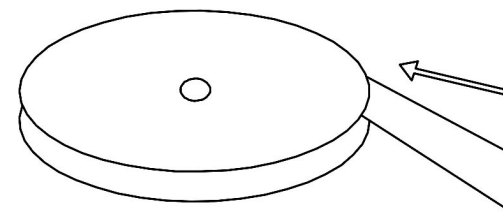
hg≤nd cr≤nd



SECTION: (A-A)



SECTION: (B-B)



**電鍍後的收料方向
After receiving
the direction
of plating

DIM	TOL	DIM	TOL
X.	/	X*	/
X.X	±0.15	X.X*	±2°
X.XX	±0.10	X.XX*	±1°
X.XXX	±0.05	X.XXX*	/

RoHS
Compliant

HSM 玄茂科技股份有限公司
HSUAN MAO TECHNOLOGY CO., LTD.

APPD.
核准
Betty
DATE 制表日
2018/03/02

SCALE
比例 參考
UNIT
單位 MM
PAGE
張數 1 OF 1
REV.
版次 A

PART NAME 品名
1.27mm SATA TERMINAL HIGH TYPE
MATERIAL:PHOSPHOR BRONZE
SUITABLE FOR 22AWG ROHS
PART NO.
料號 T1270-XPA16L0000R